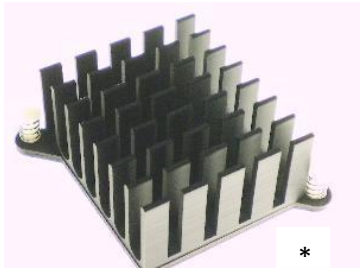
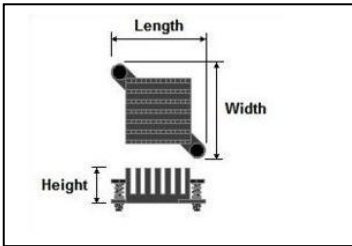




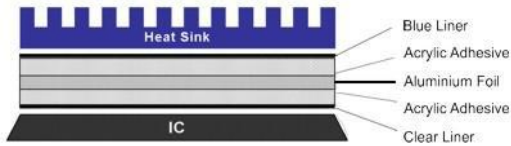
**Push Pin**



**All ABL's BGA heatsinks are supplied with thermal tape**

Model	Width	Length	Height	Pad Size	Anodised Finish	Pin Length	°C/W	°C/W
	[mm]	[mm]	[mm]	[mm]		[mm]	Natural	Forced 2M/s
BGA-PP-010	40.8	40.8	15.0	20x20	Natural	14.0	11.00	5.50
BGA-PP-015	49	49	10.0	30x30	Natural	14.0	10.50	4.20
BGA-PP-020	49	49	15.0	30x30	Natural	14.0	9.00	4.00
BGA-PP-025	49	49	15.0	30x30	Natural	16.4	9.00	4.00
BGA-PP-030	49	49	35.0	30x30	Natural	14.0	7.00	3.80
*BGA-PP-035	49	49	20.0	30x30	Black	16.4	7.00	3.70
BGA-PP-040	49	49	35.0	30x30	Black	14.0	6.50	3.50

**Thermally Conductive Aluminium Foil**



All ABL's BGA heatsinks are supplied with thermal tape.

With excellent thermal conductivity, cushioning and gap filling properties, the pad is an ideal thermal interface material specifically designed for heat sink attachment to MPU, chip set and other plastic encapsulated components.

It consists of an aluminium foil backing coated, on both sides, with a very high temperature resistance acrylic adhesive. Due to its high heat performance and adhesive properties this tape can also be used to attach components to a vertical heatsink and to metal enclosure surfaces.

Colour	-	White
Backing Type / Thickness	Mm	Aluminium Foil / 0.10
Adhesive Type / Thickness	Mm	Acrylic 0.075 (on clear liner side)
Total Thickness	mm	0,27
Adhesion	Kg/25mm	1,5
Thermal Conductivity	W/m-K	0,95
Thermal Resistance	°C-in <sup>2</sup> /W	0,2
Holding Power@23°C	Hour	>72
Holding Power @ 130°C	Hour	>2